HSMS-2802

Low reverse leakage Schottky diode

Description



Lifecycle status: Active



Features

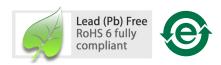
General purpose Schottky diode in a broad range of package configurations. Optimised for High voltage clamp or analog DC switch applications. For low breakdown applications, like detectors or mixers, please refer to HSMS-282X. For low flicker (1/F) noise applications refer to HSMS-281X. VBR=70 V, CT=2.0pF, RD=35 Ohms, Vf @ 1 mA=410 mV.

HSMS-280x

Surface Mount RF Schottky Barrier Diodes



Data Sheet



Description/Applications

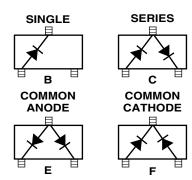
These Schottky diodes are specifically designed for both analog and digital applications. This series offers a wide range of specifications and package configurations to give the designer wide flexibility. The HSMS-280x series of diodes is optimized for high voltage applications.

Note that Avago's manufacturing techniques assure that dice found in pairs and quads are taken from adjacent sites on the wafer, assuring the highest degree of match.

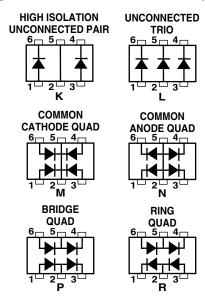
Features

- Surface Mount Packages
- High Breakdown Voltage
- Low FIT (Failure in Time) Rate*
- Six-sigma Quality Level
- Single, Dual and Quad Versions
- Tape and Reel Options Available
- Lead-free
- For more information see the Surface Mount Schottky Reliability Data Sheet.

Package Lead Code Identification, SOT-323 (Top View)



Package Lead Code Identification, SOT-363 (Top View)



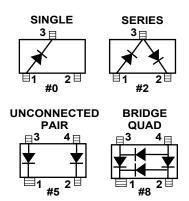
Package Lead Code Identification, SOT-23/SOT-143 (Top View)

COMMON

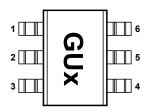
ANODE

COMMON

CATHODE



Pin Connections and Package Marking, SOT-363



Notes

- 1. Package marking provides orientation and identification.
- 2. See "Electrical Specifications" for appropriate package marking.

ESD WARNING:

Handling Precautions Should Be Taken To Avoid Static Discharge.

Absolute Maximum Ratings^[1] $T_C = 25$ °C

Symbol	Parameter	Unit	SOT-23/SOT-143	SOT-323/SOT-363
I _f	Forward Current (1 µs Pulse)	Amp	1	1
P _{IV}	Peak Inverse Voltage	V	Same as V _{BR}	Same as V _{BR}
T _j	Junction Temperature	°C	150	150
T _{stg}	Storage Temperature	°C	-65 to 150	-65 to 150
θ_{jc}	Thermal Resistance ^[2]	°C/W	500	150

Notes

- 1. Operation in excess of any one of these conditions may result in permanent damage to the device.
- 2. $T_C = +25$ °C, where T_C is defined to be the temperature at the package pins where contact is made to the circuit board.

Electrical Specifications T_A = 25°C, Single Diode [3]

Part Number HSMS ^[4]	Package Marking Code	Lead Code	Configuration	Minimum Breakdown Voltage V _{BR} (V)	Maximum Forward Voltage V _F (mV)	Maximum Forward Voltage V _F (V) @ I _F (mA)	Maximum Reverse Leakage I _R (nA) @ V _R (V)	Maximum Capacitance C _T (pF)	Typical Dynamic Resistance $R_D (\Omega)^{[5]}$
2800	A0	0	Single						,
2802	A2	2	Series						
2803	А3	3	Common Anode	_					
2804	A4	4	Common Cathode	<u>-</u>					
2805	A5	5	Unconnected Pair	<u>-</u>					
2808	A8	8	Bridge Quad ^[4]	<u>-</u>					
280B	A0	В	Single	<u>-</u>					
280C	A2	С	Series	<u>-</u>					
280E	А3	Е	Common Anode	70	410	1.0 @ 15	200 @ 50	2.0	35
280F	A4	F	Common Cathode	<u>-</u>					
280K	AK	K	High Isolation Unconnected Pair	-					
280L	AL	L	Unconnected Trio	-					
280M	Н	М	Common Cathode Quad	-					
280N	N	N	Common Anode Quad	_					
280P	AP	Р	Bridge Quad	-					
280R	0	R	Ring Quad	-					
Test Con	ditions			$I_R = 10 \text{ mA}$	$I_F = 1 \text{ mA}$			$V_F = 0 V$ f = 1 MHz	$I_F = 5 \text{ mA}$

Notes:

- 1. $\mathrm{DV_F}$ for diodes in pairs and quads in 15 mV maximum at 1 mA.
- 2. DC_{TO} for diodes in pairs and quads is 0.2 pF maximum.
- 3. Effective Carrier Lifetime (t) for all these diodes is 100 ps maximum measured with Krakauer method at 5 mA.
- 4. See section titled "Quad Capacitance."
- 5. $R_D = R_S + 5.2 \Omega$ at 25°C and $I_f = 5$ mA.

Applications Information Introduction — Product Selection

Avago's family of Schottky products provides unique solutions to many design problems.

The first step in choosing the right product is to select the diode type. All of the products in the HSMS-280x family use the same diode chip, and the same is true of the HSMS-281x and HSMS-282x families. Each family has a different set of characteristics which can be compared most easily by consulting the SPICE parameters in Table 1.

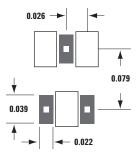
A review of these data shows that the HSMS-280x family has the highest breakdown voltage, but at the expense of a high value of series resistance ($R_{\rm s}$). In applications which do not require high voltage the HSMS-282x family, with a lower value of series resistance, will offer higher current carrying capacity and better performance. The HSMS-281x family is a hybrid Schottky (as is the HSMS-280x), offering lower 1/f or flicker noise than the HSMS-282x family.

In general, the HSMS-282x family should be the designer's first choice, with the -280x family reserved for high voltage applications and the HSMS-281x family for low flicker noise applications.

Assembly Instructions

SOT-323 PCB Footprint

A recommended PCB pad layout for the miniature SOT-323 (SC-70) package is shown in Figure 6 (dimensions are in inches). This layout provides ample allowance for package placement by automated assembly equipment without adding parasitics that could impair the performance.



Dimensions in inches

Figure 6. Recommended PCB Pad Layout for Avago's SC70 3L/SOT-323 Products.

Assembly Instructions

SOT-363 PCB Footprint

A recommended PCB pad layout for the miniature SOT-363 (SC-70, 6 lead) package is shown in Figure 7 (dimensions are in inches). This layout provides ample allowance for package placement by automated assembly equipment without adding parasitics that could impair the performance.

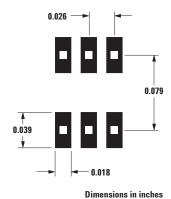


Figure 7. Recommended PCB Pad Layout for Avago's SC70 6L/SOT-363 Products.

Table 1. Typical SPICE Parameters

Parameter	Units	HSMS-280x	HSMS-281x	HSMS-282x
B _V	V	75	25	15
C_{J0}	pF	1.6	1.1	0.7
E_G	eV	0.69	0.69	0.69
I_{BV}	Α	1 E-5	1 E-5	1 E-4
Is	Α	3 E-8	4.8 E-9	2.2 E-8
N		1.08	1.08	1.08
R_S	Ω	30	10	6
P _B (V _J)	V	0.65	0.65	0.65
P _T (XTI)		2	2	2
М		0.5	0.5	0.5

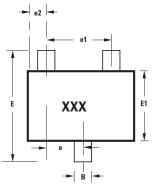
Part Number Ordering Information

	No. of	
Part Number	Devices	Container
HSMS-280x-TR2G	10000	13"Reel
HSMS-280x-TR1G	3000	7" Reel
HSMS-280x-BLKG	100	antistatic bag

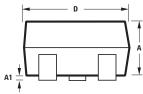
x = 0, 2, 3, 4, 5, 8, B, C, E, F, K, L, M, N, P, R

Package Dimensions

Outline 23 (SOT-23)



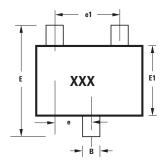


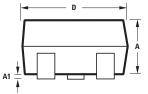


Notes: XXX-package marking Drawings are not to scale

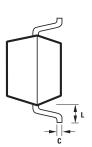
DIMENSIONS (mm) MIN. SYMBOL MAX. 0.79 1.20 A1 0.000 0.100 В 0.37 0.54 C 0.086 0.152 D 2.73 3.13 E1 1.15 1.50 0.89 1.02 e1 1.78 2.04 e2 0.45 0.60 Ε 2.10 2.70 0.45 0.69

Outline SOT-323 (SC-70 3 Lead)





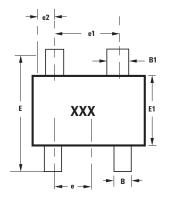
Notes: XXX-package marking Drawings are not to scale

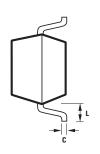


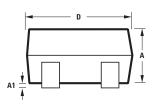
	DIMENSIONS (mm)		
SYMBOL	MIN.	MAX.	
Α	0.80	1.00	
A1	0.00	0.10	
В	0.15	0.40	
С	0.10	0.20	
D	1.80	2.25	
E1	1.10	1.40	
е	0.65 typical		
e1	1.30 typical		
E	1.80	2.40	
	0.425 typical		

Package Dimensions (Continued)

Outline 143 (SOT-143)



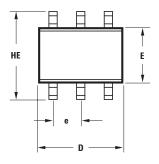




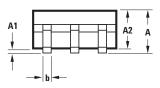
Notes: XXX-package marking Drawings are not to scale

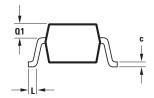
	DIMENSIONS (mm)		
SYMBOL	MIN.	MAX.	
Α	0.79	1.097	
A1	0.013	0.10	
В	0.36	0.54	
B1	0.76	0.92	
С	0.086	0.152	
D	2.80	3.06	
E1	1.20	1.40	
е	0.89	1.02	
e1	1.78	2.04	
e2	0.45	0.60	
E	2.10	2.65	
L	0.45	0.69	

Outline SOT-363 (SC-70 6 Lead)

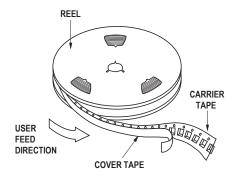


	DIMENSIONS (mm)		
SYMB0L	MIN.	MAX.	
E	1.15	1.35	
D	1.80	2.25	
HE	1.80	2.40	
Α	0.80	1.10	
A2	0.80	1.00	
A1	0.00	0.10	
01	0.10	0.40	
е	0.650 BCS		
b	0.15	0.30	
С	0.10	0.20	
L	0.10	0.30	

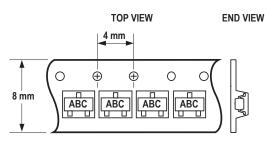




Device Orientation

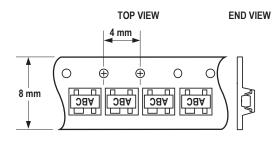


For Outlines SOT-23, -323



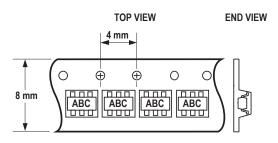
Note: "AB" represents package marking code.
"C" represents date code.

For Outline SOT-143



Note: "AB" represents package marking code.
"C" represents date code.

For Outline SOT-363



Note: "AB" represents package marking code.
"C" represents date code.